KOKI
CHALLENGING NEW TECHNOLOGIES

eco+PLUS Lead Free SOLUTIONS you can TRUST

Anti-pillow and powerful wetting solder paste

S3X48-M500C-5 Sn 3.0Ag 0.5Cu

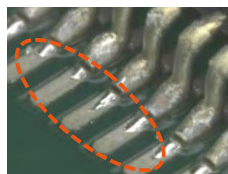
Powerful wetting to oxidized pads and components

Ultimate solution for "De-wetting"

In today's SMT field, as the applications for PCBs have increased and the types of PCB also, soldering conditions such as plating finishes, quality and base metal have been also greatly diversified. Particularly, oxidized components are a major concern as the cause of many soldering defects.

Figure 1. De-wetting due to oxidization

e.g. 1.
Oxidized Sn plated QFP pattern



e.g. 2.
Oxidized Ni base plating under Au plating

Exceptionally powerful activation

Figure 2. Wetting behavior to an oxidized pattern

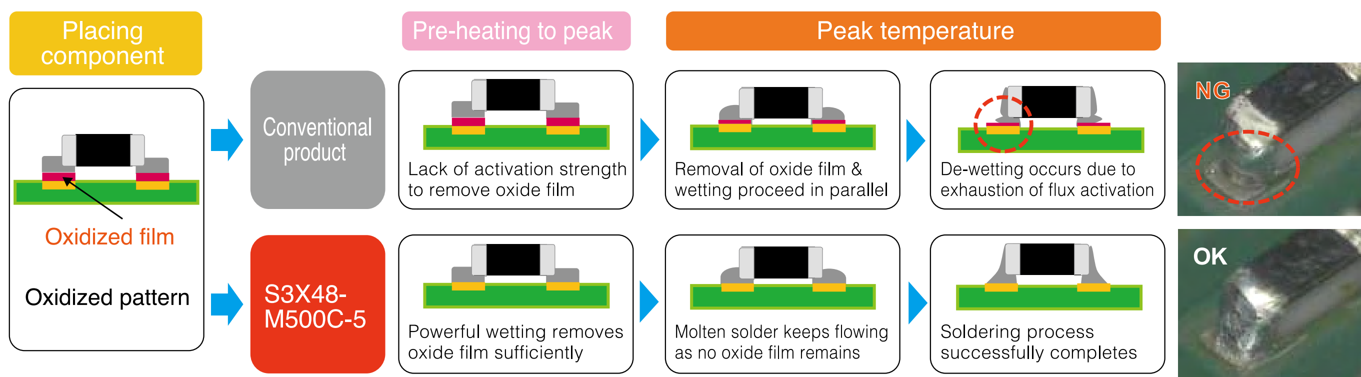


Figure 3. Comparison test of wetting behavior

●Stencil thickness: 120μm Reflow atmosphere: Air Oxidized conditions: KOKI original method

Product specifications

Product name	S3X48-M500C-5
Alloy composition (%)	Sn 3.0Ag 0.5Cu
Melting point (°C)	217-219
Particle size (μm)	20-45
Viscosity (Pa.s)	220
Flux content (%)	11.5
Halide content (%)	0
Flux type	ROL0
Optional powder size	20-38μm (Product name: S3X58-M500C-5)

Powerful wetting
Anti-pillow defect
Low voiding
Fine pitch printing >0.4mm pitch >0.3mm dia. CSP
Applicable for high pre-heating reflow
Tack time >48hours >48h
No clean type No-clean

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